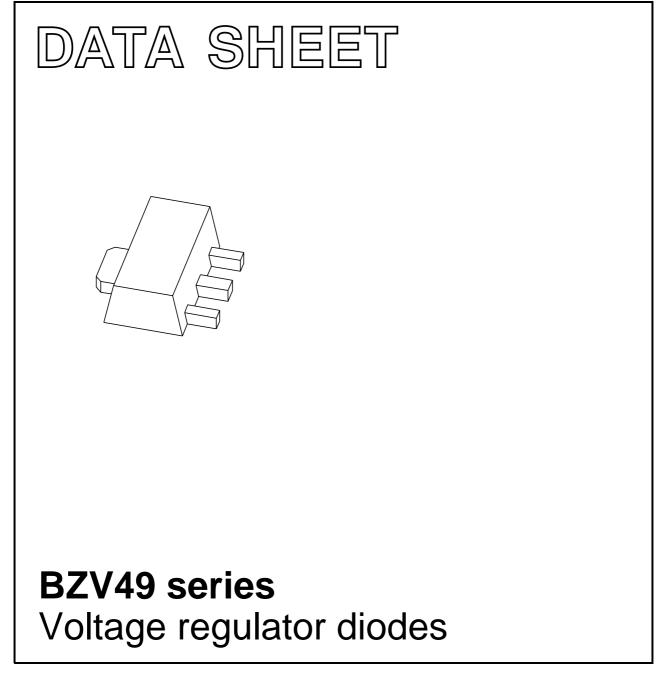
DISCRETE SEMICONDUCTORS



Product data sheet Supersedes data of 1999 May 11 2005 Feb 03



BZV49 series

FEATURES

- Total power dissipation: max. 1 W
- Tolerance series: approx. ±5%
- Working voltage range: nom. 2.4 to 75 V (E24 range)
- Non-repetitive peak reverse power dissipation: max. 40 W.

APPLICATIONS

• General regulation functions.

DESCRIPTION

Medium-power voltage regulator diodes in a SOT89 plastic SMD package.

The diodes are available in the normalized E24 approx. \pm 5% tolerance range. The series consists of 37 types with nominal working voltages from 2.4 to 75 V (BZV49-C2V4 to BZV49-C75).

PINNING

PIN	DESCRIPTION
1	anode
2	cathode
3	anode

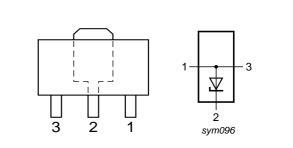


Fig.1 Simplified outline (SOT89) and symbol.

ORDERING INFORMATION

TYPE NUMBER		PACKAGE							
ITFE NUMBER	NAME	DESCRIPTION	VERSION						
BZV49-C2V4 to BZV49-C75 note 1	SC-62	plastic surface mounted package; collector pad for good heat transfer; 3 leads	SOT89						

Note

1. The series consists of 37 types with nominal working voltages from 2.4 to 75 V (E24 range).

MARKING

TYPE NUMBER	MARKING CODE	TYPE NUMBER	MARKING CODE	TYPE NUMBER	MARKING CODE	TYPE NUMBER	MARKING CODE
BZV49-C2V4	2Y4	BZV49-C6V2	6Y2	BZV49-C16	16Y	BZV49-C43	43Y
BZV49-C2V7	2Y7	BZV49-C6V8	6Y8	BZV49-C18	18Y	BZV49-C47	47Y
BZV49-C3V0	3Y0	BZV49-C7V5	7Y5	BZV49-C20	20Y	BZV49-C51	51Y
BZV49-C3Y3	3Y3	BZV49-C8V2	8Y2	BZV49-C22	22Y	BZV49-C56	56Y
BZV49-C3V6	3Y6	BZV49-C9V1	9Y1	BZV49-C24	24Y	BZV49-C62	62Y
BZV49-C3V9	3Y9	BZV49-C10	10Y	BZV49-C27	27Y	BZV49-C68	68Y
BZV49-C4V3	4Y3	BZV49-C11	11Y	BZV49-C30	30Y	BZV49-C75	75Y
BZV49-C4V7	4Y7	BZV49-C12	12Y	BZV49-C33	33Y	_	—
BZV49-C5V1	5Y1	BZV49-C13	13Y	BZV49-C36	36Y	_	_
BZV49-C5V6	5Y6	BZV49-C15	15Y	BZV49-C39	39Y	-	_

BZV49 series

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
I _F	continuous forward current		-	250	mA
I _{ZSM}	non-repetitive peak reverse current	t _p = 100 μs; square wave; T _j = 25 °C prior to surge	see Table "Per type		
P _{tot}	total power dissipation	T _{amb} = 25 °C; note 1	-	1	W
P _{ZSM}	non-repetitive peak reverse power dissipation	$t_p = 100 \ \mu s$; square wave; T _j = 25 °C prior to surge; see Fig.2	-	40	W
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		_	150	°C

Note

1. Device mounted on a ceramic substrate; area = 2.5 cm^2 ; thickness = 0.7 mm.

ELECTRICAL CHARACTERISTICS

Total series

 $T_{amb} = 25 \ ^{\circ}C$ unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MAX.	UNIT
VF	forward voltage	I _F = 50 mA; see Fig.3	1	V

Product data sheet

BZV49 series

$T_i = 25 \ ^{\circ}C$ unless otherwise specified. WORKING DIFFERENTIAL TEMP. COEFF.

BZV49- CXXX	VOLT V _Z	KING FAGE (V) ^{Ztest}	DIFFERENTIAL RESISTANCE r _{dif} (Ω) at I _{Ztest}		TEMP. COEFF. S _Z (mV/K) at I _{Ztest} see Figs 4 and 5		TEST CURRENT I _{Ztest} (mA)	ENT C_d (pF)CURRENT atREVERSmA)at f = 1 MHz;REVERSEI;at $V_R = 0 V$ VOLTAGEat t_p		NON-REPETITIVE PEAK REVERSE CURRENT I_{ZSM} (A) at $t_p = 100 \ \mu s$;		
						÷	÷			Ι_R (μΑ)	V _R	T _{amb} = 25 °C
	MIN.	MAX.	TYP.	MAX.	MIN.	TYP.	MAX.		MAX.	MAX.	(V)	MAX.
2V4	2.2	2.6	70	100	-3.5	-1.6	0	5	450	50	1.0	6.0
2V7	2.5	2.9	75	100	-3.5	-2.0	0	5	450	20	1.0	6.0
3V0	2.8	3.2	80	95	-3.5	-2.1	0	5	450	10	1.0	6.0
3V3	3.1	3.5	85	95	-3.5	-2.4	0	5	450	5	1.0	6.0
3V6	3.4	3.8	85	90	-3.5	-2.4	0	5	450	5	1.0	6.0
3V9	3.7	4.1	85	90	-3.5	-2.5	0	5	450	3	1.0	6.0
4V3	4.0	4.6	80	90	-3.5	-2.5	0	5	450	3	1.0	6.0
4V7	4.4	5.0	50	80	-3.5	-1.4	+0.2	5	300	3	2.0	6.0
5V1	4.8	5.4	40	60	-2.7	-0.8	+1.2	5	300	2	2.0	6.0
5V6	5.2	6.0	15	40	-2.0	+1.2	+2.5	5	300	1	2.0	6.0
6V2	5.8	6.6	6	10	0.4	2.3	3.7	5	200	3	4.0	6.0
6V8	6.4	7.2	6	15	1.2	3.0	4.5	5	200	2	4.0	6.0
7V5	7.0	7.9	6	15	2.5	4.0	5.3	5	150	1	5.0	4.0
8V2	7.7	8.7	6	15	3.2	4.6	6.2	5	150	0.7	5.0	4.0
9V1	8.5	9.6	6	15	3.8	5.5	7.0	5	150	0.5	6.0	3.0
10	9.4	10.6	8	20	4.5	6.4	8.0	5	90	0.2	7.0	3.0
11	10.4	11.6	10	20	5.4	7.4	9.0	5	85	0.1	8.0	2.5
12	11.4	12.7	10	25	6.0	8.4	10.0	5	85	0.1	8.0	2.5
13	12.4	14.1	10	30	7.0	9.4	11.0	5	80	0.1	8.0	2.5
15	13.8	15.6	10	30	9.2	11.4	13.0	5	75	0.05	10.5	2.0
16	15.3	17.1	10	40	10.4	12.4	14.0	5	75	0.05	11.2	1.5
18	16.8	19.1	10	45	12.4	14.4	16.0	5	70	0.05	12.6	1.5
20	18.8	21.2	15	55	14.4	16.4	18.0	5	60	0.05	14.0	1.5
22	20.8	23.3	20	55	16.4	18.4	20.0	5	60	0.05	15.4	1.25
24	22.8	25.6	25	70	18.4	20.4	22.0	5	55	0.05	16.8	1.25

Per type 2005 Feb 03

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BZV49- CXXX	VOL V _Z	KING FAGE (V) Ztest	DIFFERENTIAL RESISTANCE r _{dif} (Ω) at I _{Ztest}		S	TEMP. COEFF. S _Z (mV/K) at I _{Ztest} see Figs 4 and 5		TEST CURRENT I _{Ztest} (mA)	DIODE CAP. C_d (pF) at f = 1 MHz; at V _R = 0 V	REVERSE CURRENT at REVERSE VOLTAGE		CURRENT at REVERSE		NON-REPETITIVE PEAK REVERSE CURRENT I_{ZSM} (A) at t _p = 100 μ s;
O /O/O/										I _R (μΑ) V _R		T _{amb} = 25 ℃		
	MIN.	MAX.	TYP.	MAX.	MIN.	TYP.	MAX.		MAX.	MAX.	(V)	MAX.		
27	25.1	28.9	25	80	21.4	23.4	25.3	2	50	0.05	18.9	1.0		
30	28.0	32.0	30	80	24.4	26.6	29.4	2	50	0.05	21.0	1.0		
33	31.0	35.0	35	80	27.4	29.7	33.4	2	45	0.05	23.1	0.9		
36	34.0	38.0	35	90	30.4	33.0	37.4	2	45	0.05	25.2	0.8		
39	37.0	41.0	40	130	33.4	36.4	41.2	2	45	0.05	27.3	0.7		
43	40.0	46.0	45	150	37.6	41.2	46.6	2	40	0.05	30.1	0.6		
47	44.0	50.0	50	170	42.0	46.1	51.8	2	40	0.05	32.9	0.5		
51	48.0	54.0	60	180	46.6	51.0	57.2	2	40	0.05	35.7	0.4		
56	52.0	60.0	70	200	52.2	57.0	63.8	2	40	0.05	39.2	0.3		
62	58.0	66.0	80	215	58.8	64.4	71.6	2	35	0.05	43.4	0.3		
68	64.0	72.0	90	240	65.6	71.7	79.8	2	35	0.05	47.6	0.25		
75	70.0	79.0	95	255	73.4	80.2	88.6	2	35	0.05	52.5	0.2		

NXP Semiconductors

BZV49 series

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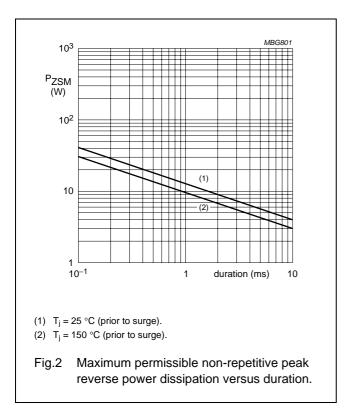
THERMAL CHARACTERISTICS

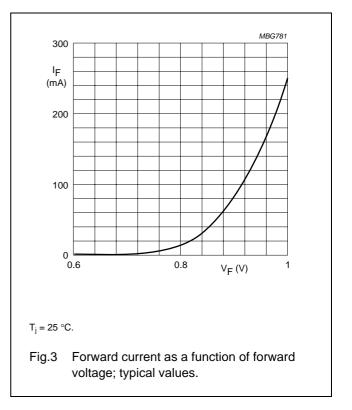
SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th(j-tp)}	thermal resistance from junction to tie-point		15	K/W
R _{th(j-a)}	thermal resistance from junction to ambient	note 1	125	K/W

Note

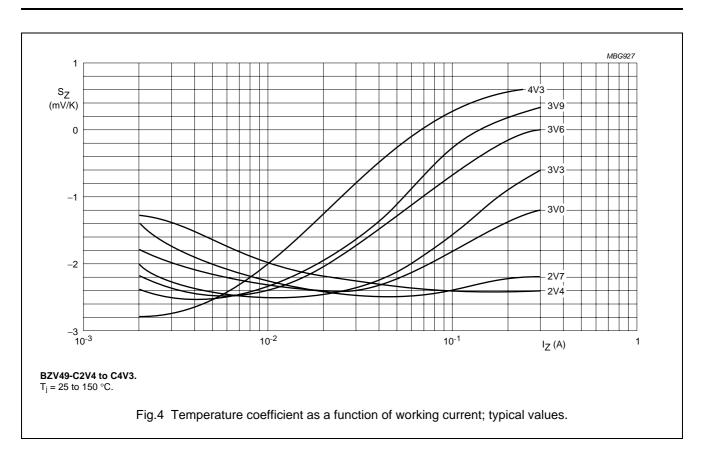
1. Device mounted on a ceramic substrate; area = 2.5 cm^2 ; thickness = 0.7 mm.

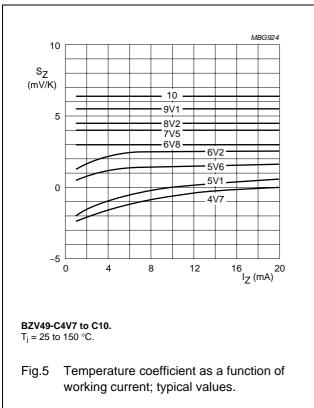
GRAPHICAL DATA





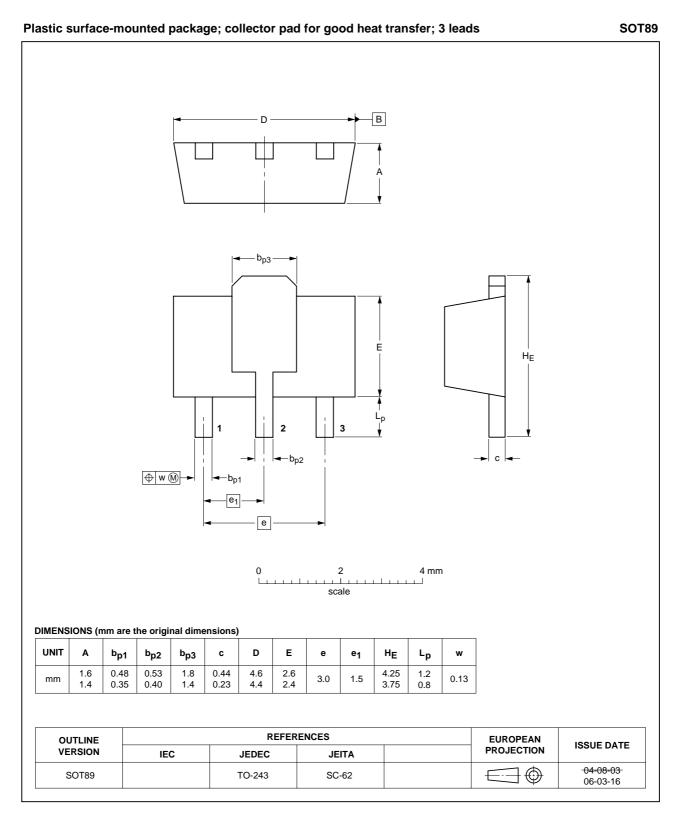
BZV49 series





BZV49 series

PACKAGE OUTLINE



BZV49 series

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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